Materials Declaration

Package	LQFP
Body Size	10 X 10
LeadCount	52
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	9.32 E-03	31905
SiO2 Filler	86	1.00 E-01	342984
Phenol Resin	5	5.82 E-03	19941
Antimony_Sb2O3	0.4	4.66 E-04	1595
Brominated Resin	0.4	4.66 E-04	1595
Carbon Black	0.2	2.33 E-04	798

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.07 E-01	366768
Ni	3	3.34 E-03	11438
Si	0.65	7.24 E-04	2478
Mg	0.15	1.67 E-04	572

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.38 E-03	8141

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.98 E-03	13638

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.42 E-03	4854

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.14 E-02	176169

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	1.30 E-03	4452
Ag Filler	74	3.70 E-03	12672

Package Totals

Weight (g)	PPM
2.92 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-ST-C

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

Materials Declaration

Package	LQFP
Body Size	10 X 10
LeadCount	52
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	9.32 E-03	31905
SiO2 Filler	86	1.00 E-01	342984
Phenol Resin	5	5.82 E-03	19941
Antimony_Sb2O3	0.4	4.66 E-04	1595
Brominated Resin	0.4	4.66 E-04	1595
Carbon Black	0.2	2.33 E-04	798

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.07 E-01	366768
Ni	3	3.34 E-03	11438
Si	0.65	7.24 E-04	2478
Mg	0.15	1.67 E-04	572

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.38 E-03	8141

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	3.38 E-03	11592
Pb	15	5.97 E-04	2046

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.42 E-03	4854

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.14 E-02	176169

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	1.30 E-03	4452
Ag Filler	74	3.70 E-03	12672

Package Totals

Weight (g)	PPM
2.92 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-ST-A

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.